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(54) PRINTED WIRING BOARD

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(57)**ABSTRACT**

A printed wiring board includes resin insulating layers, and conductor layers laminated on the resin insulating layers, respectively. The conductor layers includes a conductor layer including a conductor circuit formed such that the conductor circuit has recesses each having a depth of $2.0\,\mu m$ or more and a bottom whose diameter is larger than a diameter of an opening part of a respective one of the recesses.

